

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kyung-Hoon KIM	11/06/2008
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eup, Icheon-si
City:	Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	467-701
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12266693
CORRESPONDENCE DATA	
Fax Number:	(202)756-8087
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-756-8000
Email:	kmaramba@mwe.com
Correspondent Name:	MCDERMOTT WILL & EMERY LLP
Address Line 1:	600 13TH STREET, N.W.
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20005-3096
ATTORNEY DOCKET NUMBER:	070679-0348
NAME OF SUBMITTER:	Stephen A. Becker
Total Attachments: 3 source=0706790348assign#page1.tif source=0706790348assign#page2.tif source=0706790348assign#page3.tif	

CH \$40.00 12266693

RECORDATION FORM COVER SHEET

**Docket No.: 070679-0348**

**PATENTS ONLY**

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of Conveying Party(ies)**

**Kyung-Hoon KIM, Dae-Han KWON, Taek-Sang SONG**

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

**2. Name and address of receiving party(ies)**

Name: **HYNIX SEMICONDUCTOR INC.**

Internal Address:

Address: **San 136-1, Ami-ri, Bubal-eup, Icheon-si,  
Gyeonggi-do 467-701, REPUBLIC OF KOREA**

Additional name(s) & address(es) attached? ☐ Yes ☐ No

**3. Nature of Conveyance/Execution Date(s)**

Execution Date(s): **November 6, 2008**

- ☒ **Assignment** ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

**4. Application or patent number(s):**

A. Patent Application No(s).

☒ **This document is being filed together with a new application.**

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: **MCDERMOTT WILL & EMERY LLP**

Internal Address:

Street Address: **600 13th Street, N.W.**

City: **Washington** State: **D. C.** Zip: **20005-3096**

Phone Number: **202.756.8000**

Fax Number: **202.756.8087**

Email Address:

**6. Total number of applications and patents involved: 1**

**7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00**

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information:**

- a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number **500417**  
Authorized User Name \_\_\_\_\_

**9. Signature.**

**Stephen A. Becker 26,527**

*Stephen A. Becker* **600,295**

**November 7, 2008**

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: **3**

(SAB)

Docket No.: \_\_\_\_\_

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned

**KIM, Kyung-Hoon and KWON, Dae-Han ;and SONG, Taek-Sang**

who has made a certain new and useful invention, hereby sells, assigns and transfers unto  
Hynix Semiconductor Inc.

of San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the  
United States of America as defined in 35 U.S.C. 100 in the invention entitled  
BANDGAP REFERENCE GENERATING CIRCUIT

(a) for which an application for United States Letters Patent was filed on  
\_\_\_\_\_, and identified by United States Serial No.  
\_\_\_\_\_ ; or

(b) for which an application for United States Letters Patent was executed on  
\_\_\_\_\_ ,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

Kim Kyung Hoon  
Name: **KIM, Kyung-Hoon**

November 6 , 2008

INVENTOR

DATE SIGNED

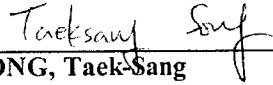


November 6 , 2008

Name: KWON, Dae-Han

INVENTOR

DATE SIGNED



November 6 , 2008

Name: SONG, Taek-Sang